US00D612879S

# (12) United States Design Patent

**Nagasaka**

(10) **Patent No.:** **US D612,879 S**

(45) **Date of Patent:** ** **Mar. 30, 2010**

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(54) **SEMICONDUCTOR WAFER INSPECTION APPARATUS**

(75) Inventor: **Munetoshi Nagasaka**, Nirasaki (JP)

(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/257,350**

(22) Filed: **Apr. 4, 2006**

(30) **Foreign Application Priority Data**

Oct. 18, 1920 (JP) ............................ 2005-030374

(51) **LOC (9) Cl.** ................................................ **15-99**

(52) **U.S. Cl.** .................................................... **D15/199**

(58) **Field of Classification Search** ................ D15/122, D15/199; 250/310; 324/751; 356/237, 237.2, 356/237.4, 237.5; 359/884

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

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## (57) CLAIM

The ornamental design for a semiconductor wafer inspection apparatus, as shown and described.

## DESCRIPTION

FIG. **1** is a front elevational view of a semiconductor wafer inspection apparatus, showing my new design;

FIG. **2** is a bottom view thereof;

FIG. **3** is a right side elevational view thereof;

FIG. **4** is a left side elevational view thereof;

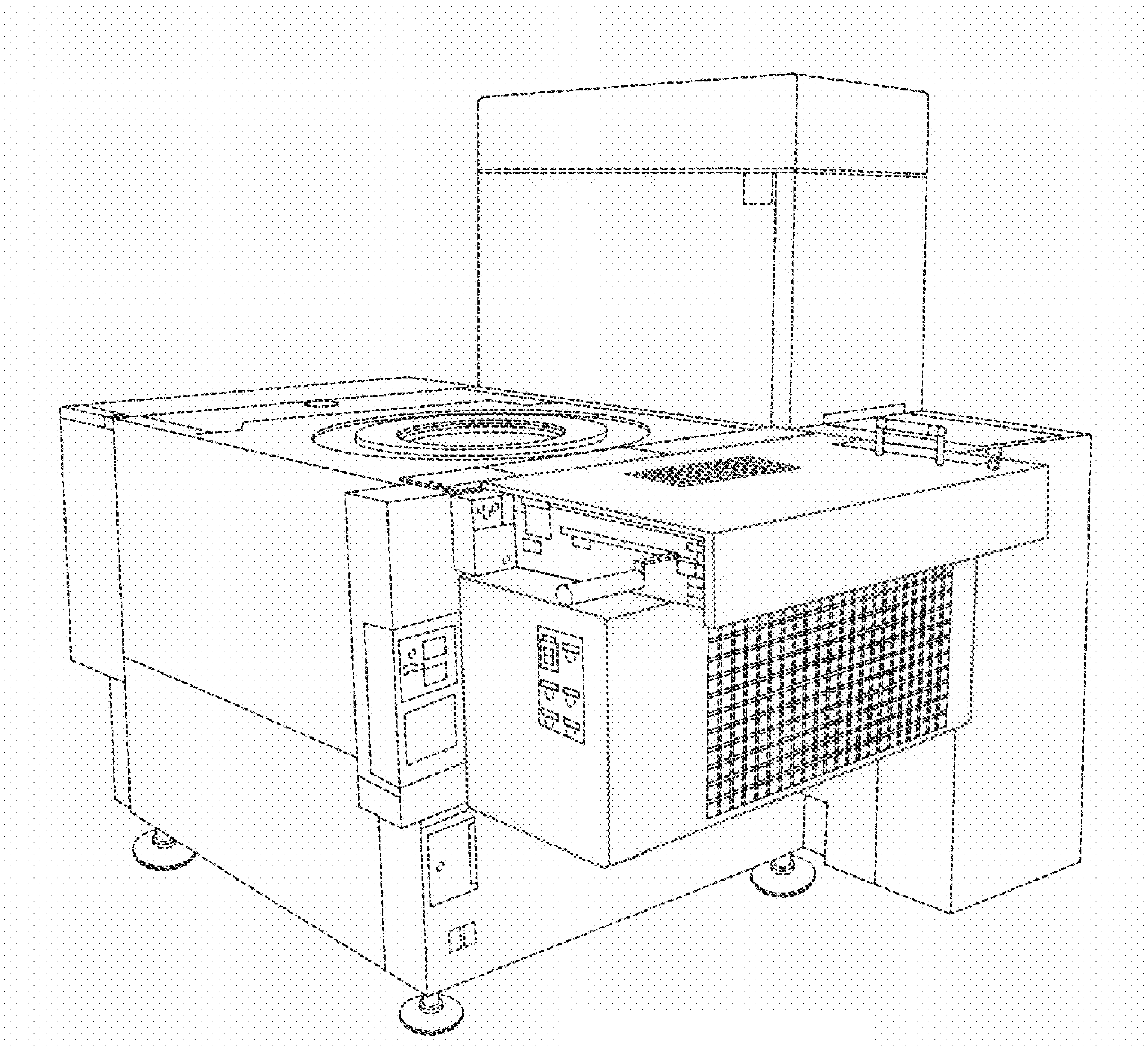
FIG. **5** is a top view thereof;

FIG. **6** is a rear elevational view thereof; and,

FIG. **7** is a perspective view thereof.

The broken line showing in each of the figures is for illustrative purposes only and forms no part of the claimed design.

**1 Claim, 7 Drawing Sheets**



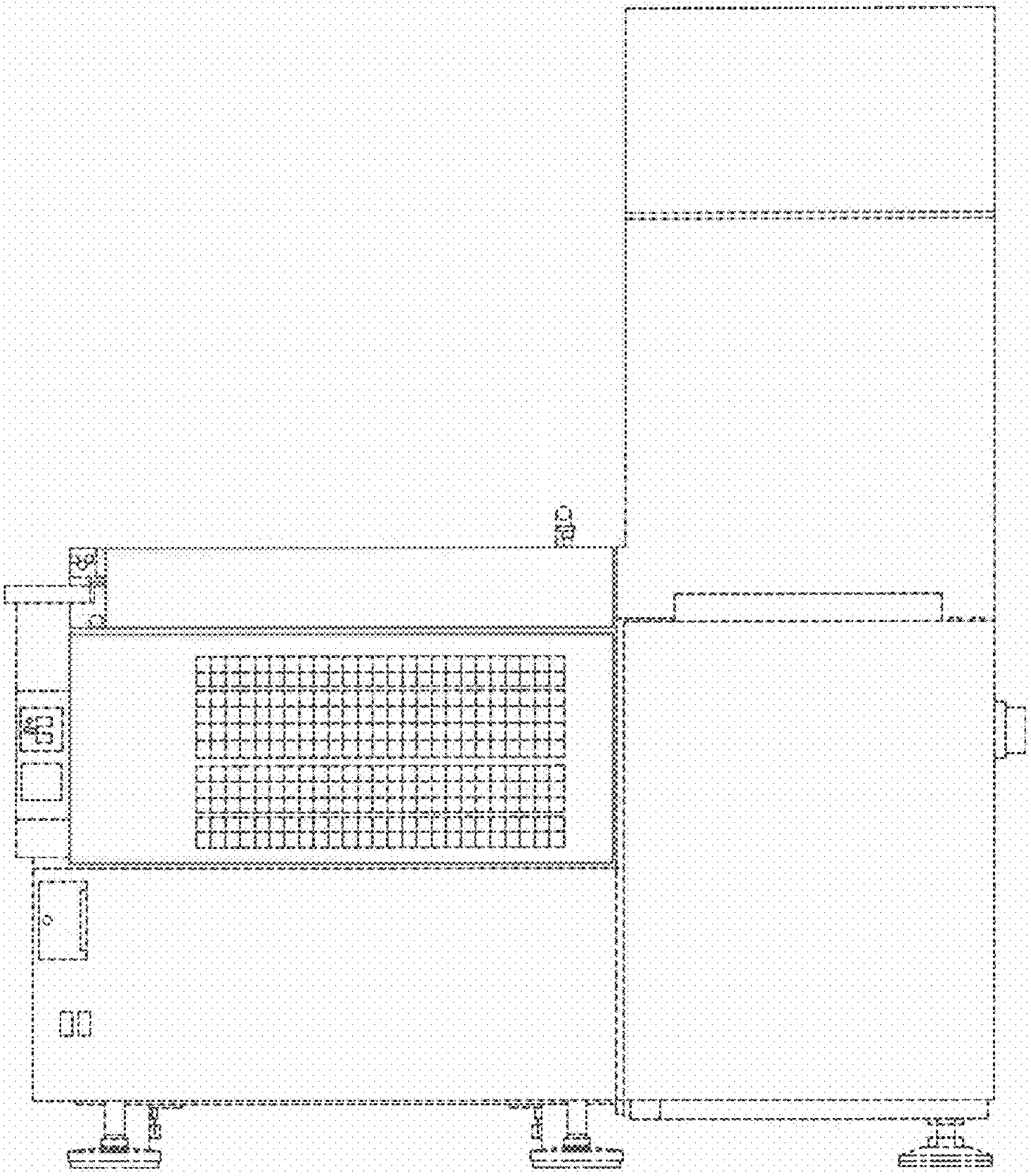


*Fig. 1*

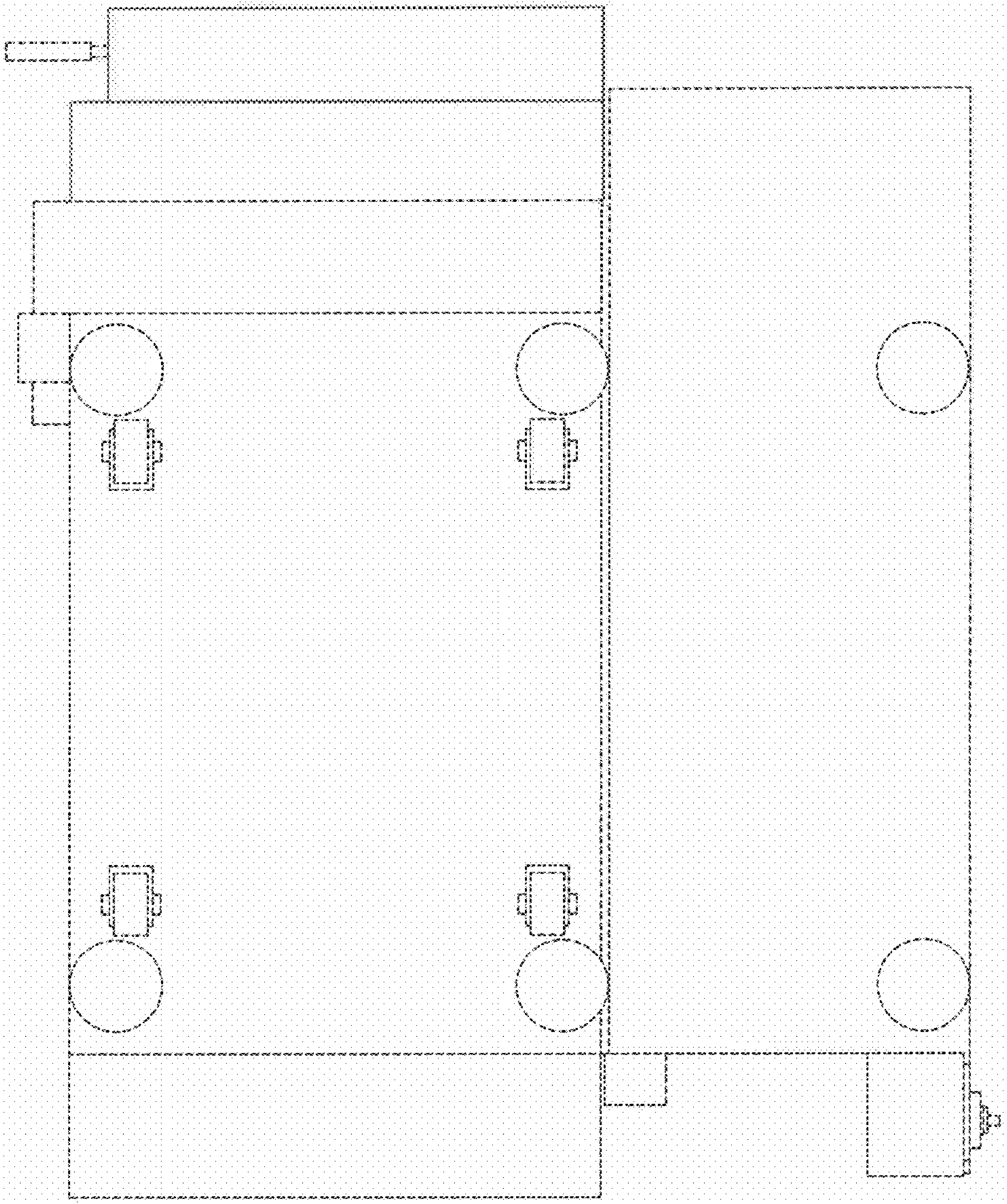


*Fig. 2*

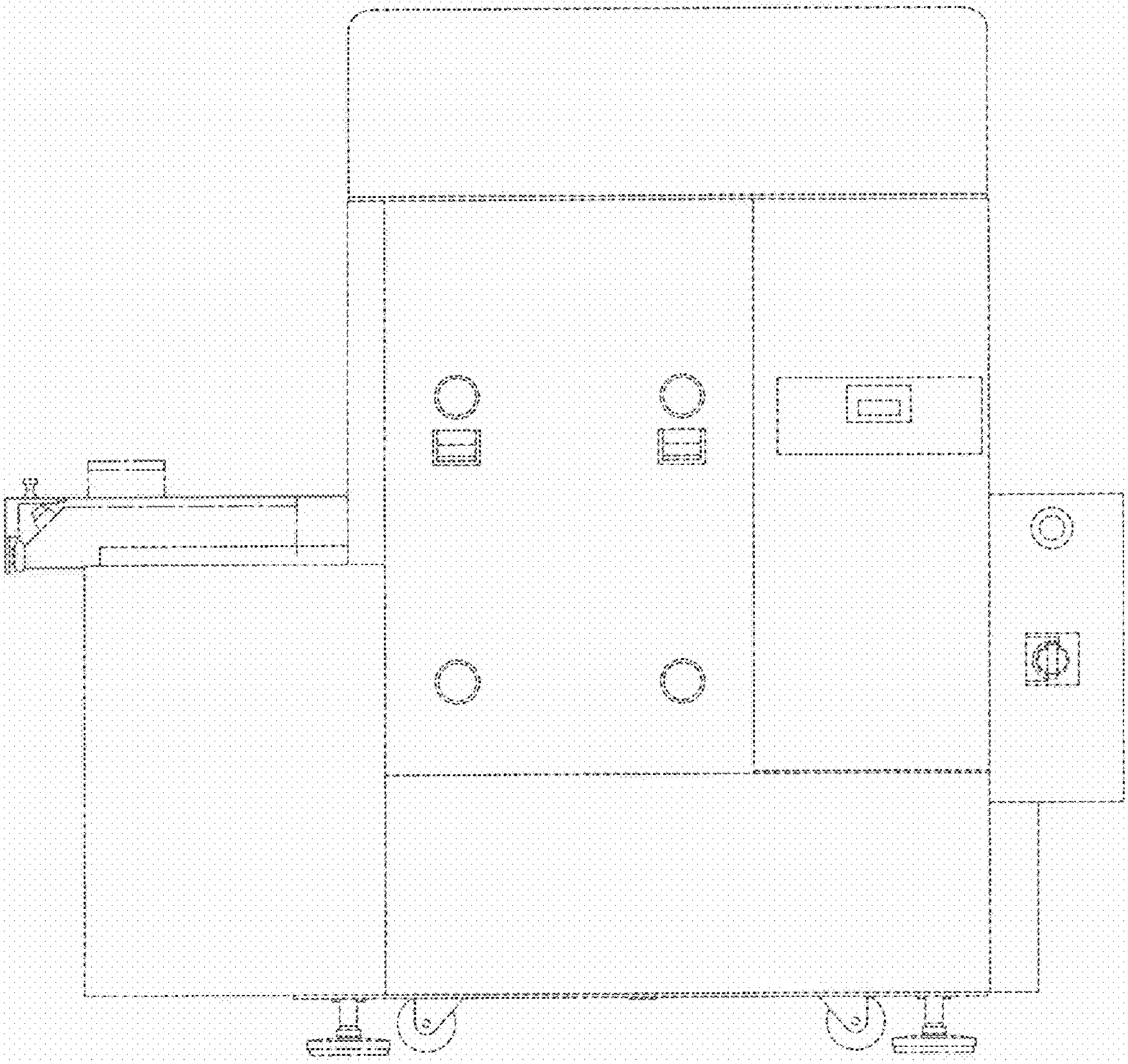


*Fig.3*

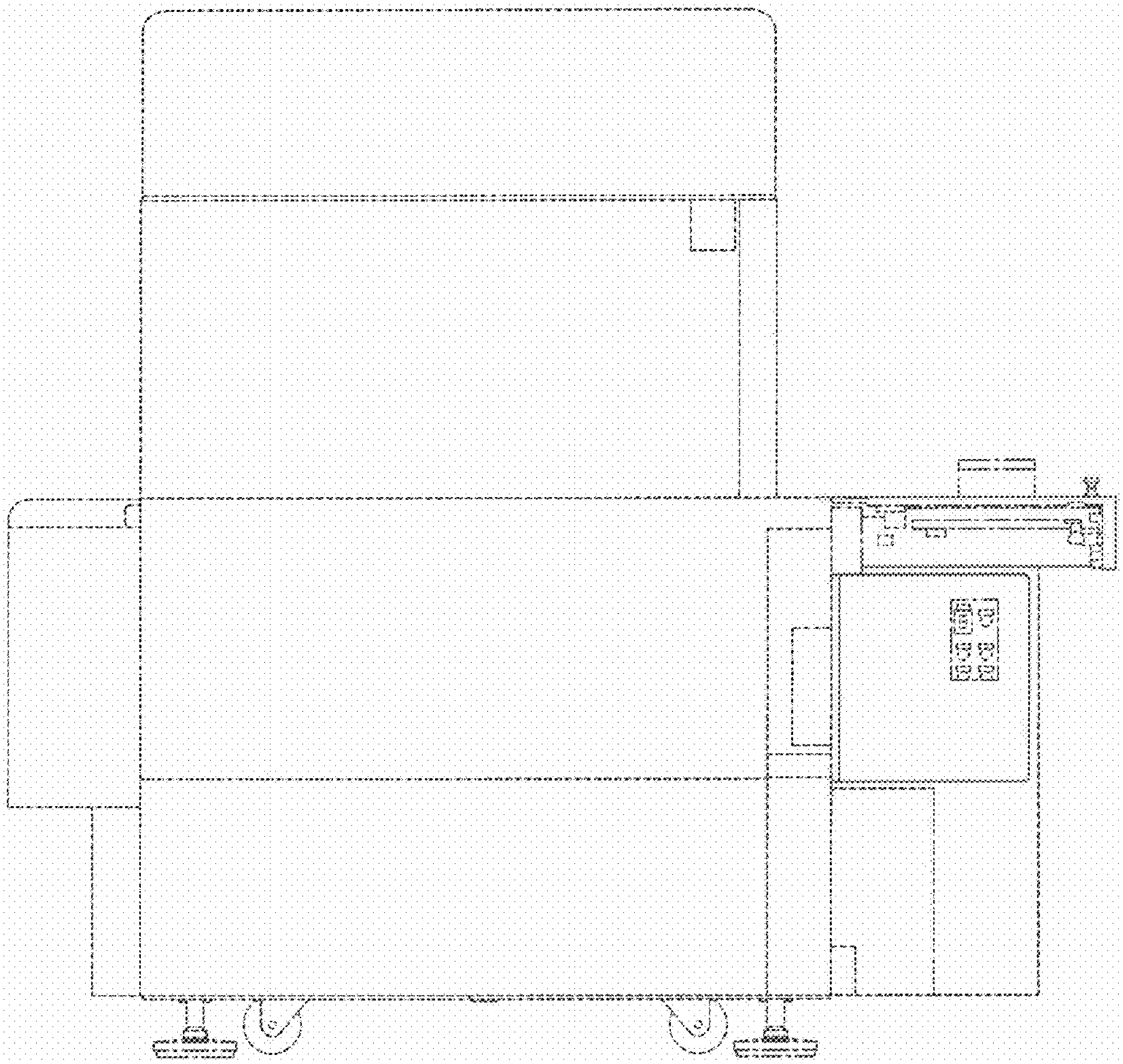


*Fig. 4*

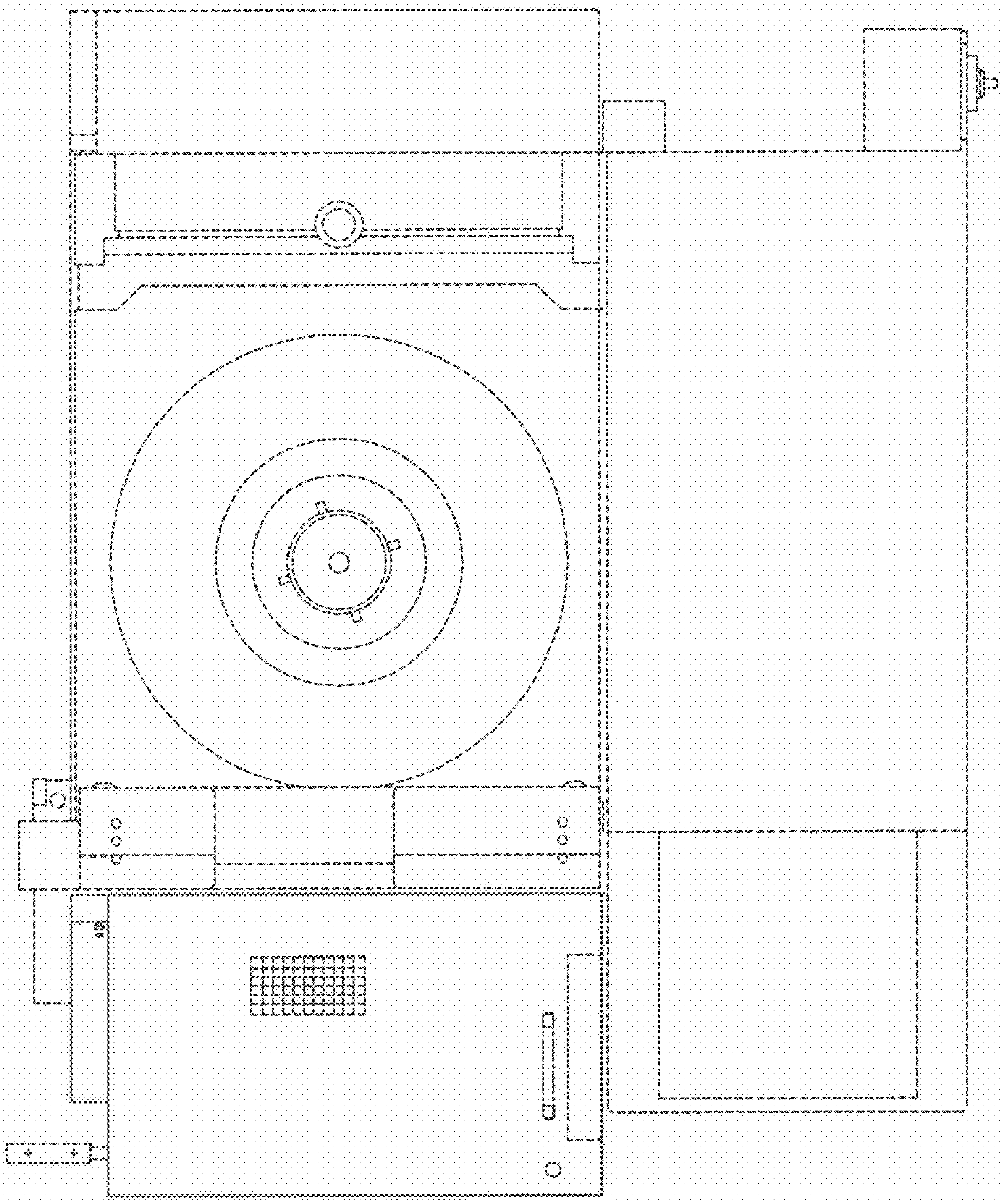


*Fig.5*

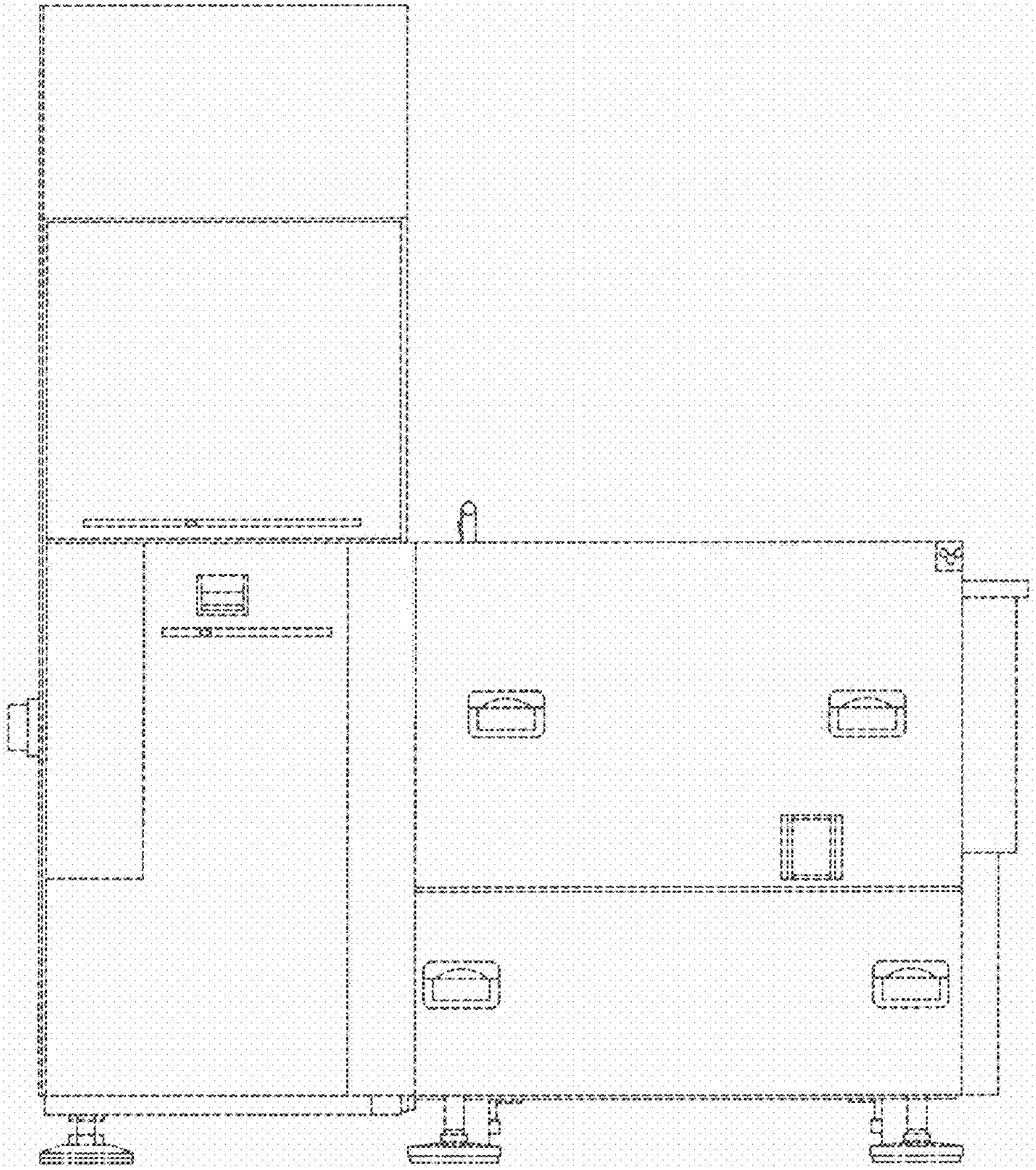


*Fig. 6*

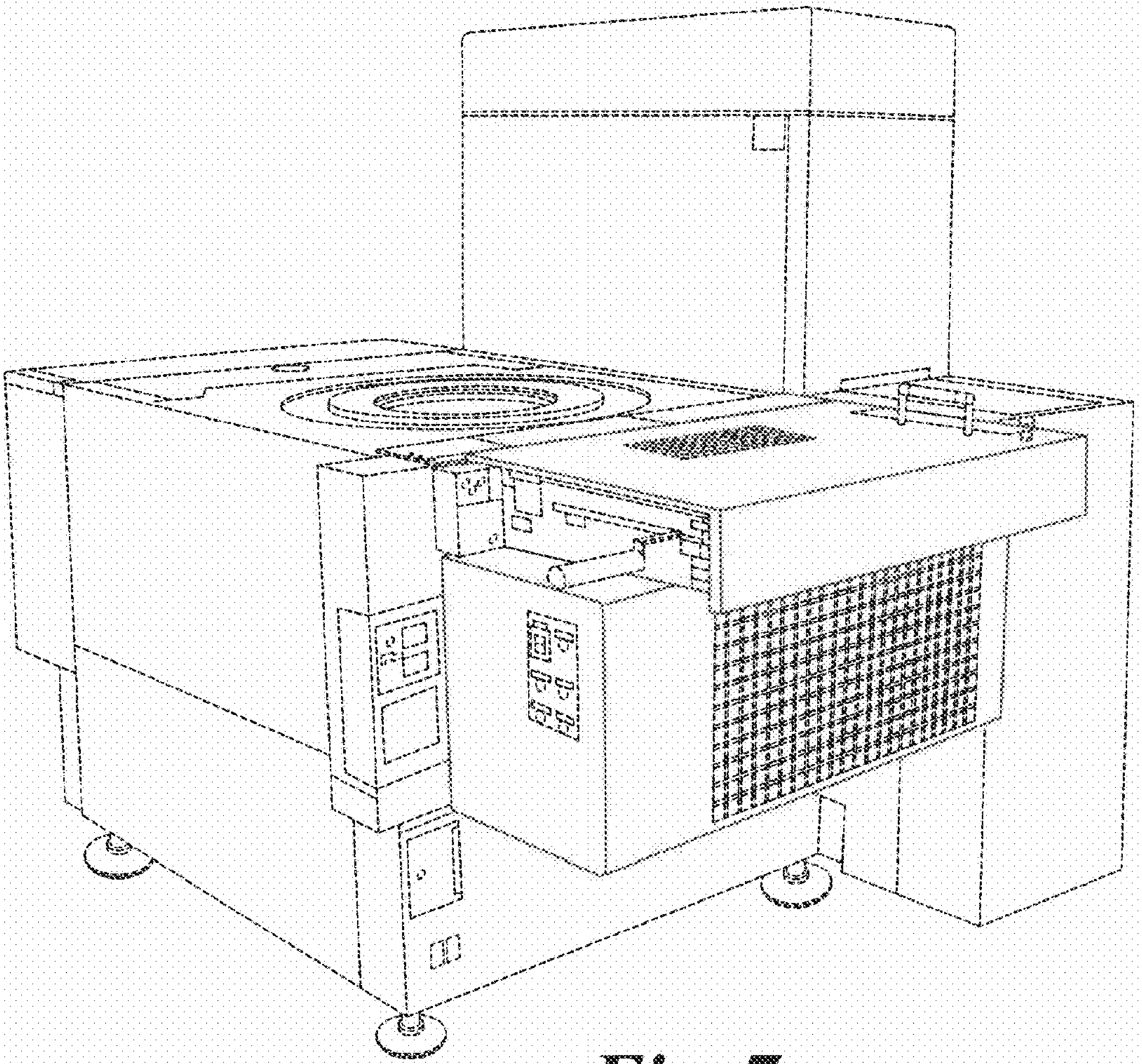


*Fig. 7*

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# CERTIFICATE OF CORRECTION

| | | |
|---|---|---|
| PATENT NO. | : Des. 612,879 S | Page 1 of 1 |
| APPLICATION NO. | : 29/257350 | |
| DATED | : March 30, 2010 | |
| INVENTOR(S) | : Nagasaka | |

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, Item (30), the Foreign Application Priority Data is incorrect. Item (30) should read:

-- (30) **Foreign Application Priority Data**

Oct. 18, 2005 (JP) ............................. 2005-030374 --

Signed and Sealed this

Eighth Day of June, 2010

David J. Kappos

David J. Kappos
*Director of the United States Patent and Trademark Office*